

Appl. No. 09/871,993

Amdt. dated July 11, 2003

Reply to Office Action of April 9, 2003

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

1. (currently amended) A packaging process for an image sensing component of which comprising a printed circuit board, a carrier, and a glass plate; wherein said printed circuit board is, ~~said carrier, and said glass plate being~~ placed in a main tray, said carrier is placed in a first tray, and said glass plate is placed in a second tray respectively for the packaging process, comprising: ~~the steps of,~~

performing a rinsing process on said printed circuit board, said carrier, and said glass plate in said main tray, said first tray, and said second tray respectively as a pre-treatment;

dispensing said printed circuit board, and then capturing said carrier in said first tray onto ~~each of~~ said printed circuit board of said main tray;

performing a thermal pressing process and an adhering process on said printed circuit board and said carrier;

dispensing said glass plate, and then collecting said carrier in said first tray to ~~each~~ said printed circuit board of said main tray; and

adhering said glass plate onto said carrier by thermal pressing in the high-pressure working environment.

2. (currently amended) A packaging process for an image sensing component as claimed in claim 1, wherein said pre-treatment of the rinsing process further comprising ~~the steps of~~:

performing a defatted rinsing, which rinses the component in a neutral rinsing solution to remove organic substance and impurities by means of supersonic vibration;

Appl. No. 09/871,993

Amdt. dated July 11, 2003

Reply to Office Action of April 9, 2003

performing a pure water rinsing, which rinses the component in a deionized pure water to remove organic substance and impurities by means of supersonic vibration; and  
baking the component to remove moisture.

3. (currently amended) A packaging process for an image sensing component as claimed in claim 1, wherein said pre-treatment of the rinsing process for the glass plate comprising ~~the steps of:~~

performing a pure water rinsing, which rinses the component in a deionized pure water to remove organic substance and impurities by means of supersonic vibration; and  
baking the component to remove moisture.

4. (original) A packaging process for an image sensing component as claimed in claim 1, wherein said carrier being made of plastic material with the properties of high density, high temperature resistance, and low humidity.

5. (original) A packaging process for an image sensing component as claimed in claim 1, wherein said high-pressure gas being one selected from nitrogen and helium, and its pressure ranging from 8 Kg/cm<sup>2</sup> to 12 Kg/cm<sup>2</sup>.

6. (original) A packaging process for an image sensing component as claimed in claim 1, wherein said adhering process for the printed circuit board and the carrier further comprising a chip adhering process and a conductive wire mounting.

7. (original) A packaging process for an image sensing component as claimed in claim 6, wherein said chip adhering process further comprising the process of low-temperature cooling, nitrogen blowing, and baking.

Appl. No. 09/871,993

Amdt. dated July 11, 2003

Reply to Office Action of April 9, 2003

8. (original) A packaging process for an image sensing component as claimed in claim 1, wherein said dispenser being one selected from gluing and silkscreen.

9-12. (canceled)